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(54) **SEMICONDUCTOR PACKAGES HAVING CAPACITORS**

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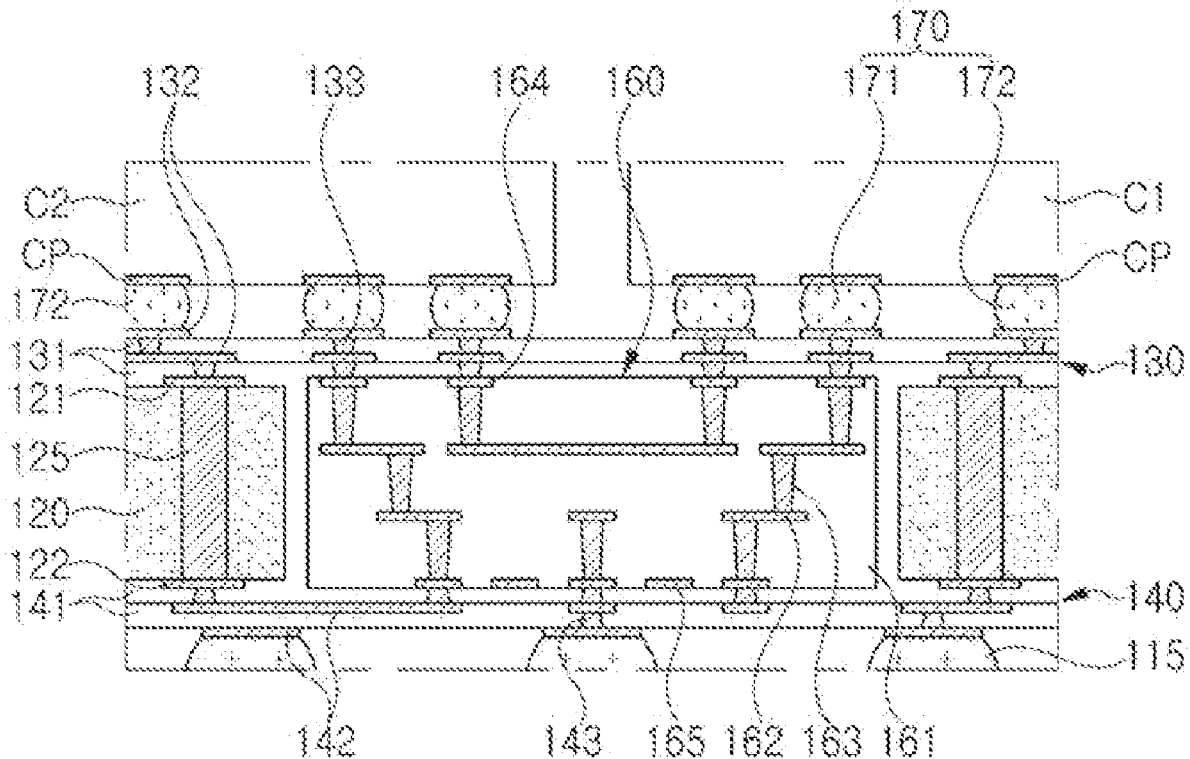
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ABSTRACT

A semiconductor package includes a package substrate, an interposer above the package substrate, a connection terminal between the package substrate and the interposer, a first semiconductor chip and a second semiconductor chip above the interposer, a bridge in the interposer, the bridge connected to the first semiconductor chip and the second semiconductor chip, a capacitor structure in the interposer, the capacitor structure including an upper structure including an upper capacitor and a lower structure including a lower capacitor, and a chip connection terminal including at least one first chip connection terminal between the interposer and the first semiconductor chip and at least one second chip connection terminal between the interposer and the second semiconductor chip.



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